

**ABSTRACT OF THE DISCLOSURE**

A plurality of semiconductor devices is placed in pockets of a tray with terminal surfaces facing upward. Positions of bump terminals of the semiconductor devices are adjusted relative to the tray. The tray is successively moved such that the bump terminals of the semiconductor devices are successively placed at a testing position. The semiconductor devices are successively tested at the testing position by, for example, contacting test electrodes to the bump terminals.